

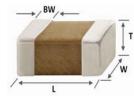
## Specification of Automotive MLCC (Reference sheet)



- Supplier : Samsung Electro-Mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL10B221KB8WPNC
- Description : CAP, 220pF, 50V, ± 10%, X7R, 0603
- AEC-Q200 Qualified

## A. Dimension





	Size	0603 inch
	L	1.60±0.10 mm
	W	0.80±0.10 mm
	Т	0.80±0.10 mm
	BW	0.30±0.20 mm

## B. Samsung Part Number

<u>c</u>	<u>:L</u>	<u>10</u>	<u>B</u>	<u>221</u>	<u>K</u>	B	<u>8</u>	w	<u>P</u>	N	<u>c</u>
(	D	2	3	4	5	6	$\bigcirc$	8	9	1	1

1 Series	Samsung Multi-layer Ceramic Capacitor		
② Size	0603 (inch code)	L: 1.60±0.10 mm	W :0.80±0.10 mm
③ Dielectric	X7R	⑧ Inner electrode	Ni, Open Mode Design
④ Capacitance	<b>220</b> pF	Termination	Metal-Epoxy
5 Capacitance	± 10%	Plating	Sn 100% (Pb Free)
tolerance		9 Product	Automotive
⑥ Rated Voltage	50 V	Special code	Normal
⑦ Thickness	0.80±0.10 mm	1 Packaging	Cardboard Type, 7" Reel

C. Reliability Test and Judgement condition

Test items	Performance	Test condition		
High Temperature	Appearance : No abnormal exterior appearance	Unpowered, 1,000hrs @ Max. temperature		
Exposure	Capacitance Change Within ±10 %	Measurement at 24±2hrs after test conclusion		
	Tan δ : 0.03 max.			
	IR :More than 10,000 <sup>№</sup> or 500 <sup>№</sup> ×µ <sup></sup>	Initial Measurement 2*		
	Whichever is smaller	Final Measurement 3*		
Temperature Cycling	Appearance : No abnormal exterior appearance	1,000Cycles		
	Capacitance Change Within ±10 %	Initial Measurement 2*		
	Tan δ :0.03 max.	Final Measurement 3*		
	IR : More than 10,000 $^{M\Omega}$ or 500 $^{M\Omega}$ × $\mu$ F	Measurement at 24±2hrs after test conclusion		
	Whichever is smaller	1 cycle condition : -55+0/-3 °C (30±3min) → Room Temp. (1min)		
		→ 125+3/-0 $^{\circ}$ C (30±3min) → Room Temp. (1min)		
Destructive Physical	No Defects or abnormalities	Per EIA 469		
Analysis				
Humidity Bias	Appearance : No abnormal exterior appearance	1,000hrs 85 °C/85%RH, Rated Voltage and 1.3~1.5V,		
	Capacitance Change Within ±12.5 %	Add 100kohm resistor		
	Tan δ :0.035 max.	Initial Measurement 2*		
	IR :More than 500 <sup>MQ</sup> or 25 <sup>MQ</sup> × $\mu$ F	Final Measurement 4*		
	Whichever is smaller	Measurement at 24±2hrs after test conclusion		
		The charge/discharge current is less than 50mA.		
High Temperature	Appearance : No abnormal exterior appearance	1,000hrs @ 125°C, 200% Rated Voltage,		
Operating Life	Capacitance Change Within ±12.5 %	Initial Measurement 2*		
	Tan δ :0.035 max.	Final Measurement 4*		
	IR :More than 1,000 <sup>№</sup> or 50 <sup>№</sup> ×µ <sup>F</sup>	Measurement at 24±2hrs after test conclusion		
	Whichever is smaller	The charge/discharge current is less than 50mA.		

	Performance	Test condition					
External Visual	No abnormal exterior appearance	Microscope ('10)					
Physical Dimension	Within the specified dimensions	Using The calipers					
Mechanical Shock	Appearance : No abnormal exterior appearance	Three shocks in each direction should be applied along					
	Capacitance Change Within ±10 %	3 mutually perpendicular axes of the test specimen (18 shocks)					
	Tan δ, IR : Initial spec.	Peak value Duration Wave Velocity					
		1,500G 0.5ms Half sine 4.7m/sec					
		Initial Measurement 2*					
		Final Measurement 5*					
Vibration	Appearance : No abnormal exterior appearance 5g's for 20min., 12cycles each of 3 orientations,						
	Capacitance Change Within ±10 %	Use 8"×5" PCB 0.031" Thick 7 secure points on one long side					
	Tan δ, IR : Initial spec.	and 2 secure points at corners of opposite sides. Parts mounted					
		within 2" from any secure point. Test from 10~2,000 $\text{Hz}.$					
		Initial Measurement 2*					
		Final Measurement 5*					
Resistance to	Appearance : No abnormal exterior appearance	preheating : 150℃ for 60~120 sec.					
Solder Heat	Capacitance Change Within ±10 %	Solder pot : 260±5℃, 10±1sec.					
	Tan δ, IR : Initial spec.	Initial Measurement 2*					
		Final Measurement 3*					
ESD	Appearance : No abnormal exterior appearance	AEC-Q200-002 or ISO/DIS10605					
	Capacitance Change Within ±10 %	Initial Measurement 2*					
	Tan δ, IR : Initial spec.	Final Measurement 4*					
Solderability	95% of the terminations is to be soldered	a) Preheat at 155 °C for 4 hours, Immerse in solder for 5s at 24					
	evenly and continuously	b) Steam aging for 8 hours, Immerse in solder for 5s at 245 $\pm$ 5 °C					
		c) Steam aging for 8 hours, Immerse in solder for 120s at 260±5 °C					
		solder : a solution ethanol and rosin					
Electrical	Capacitance : Within specified tolerance	*A capacitor prior to measuring the capacitance is heat treated at					
Characterization	Tan $\delta$ : 0.025 max.	150 +0/-10 °C for 1 hour and maintained in ambient air for $24\pm 2$ hours					
	IR(25℃): More than 10,000 <sup>M</sup> or 500 <sup>M</sup> ×µ <sup>F</sup> Whichever is smaller	The Capacitance / D.F. should be measured at $25^{\circ}$ C, 1 kHz ± 10%, 1 ± 0.2 Vrms					
	IR(125 °C) More than 1,000 MΩ or 10 MΩ× $\mu$ F	I.R. should be measured with a DC voltage not exceeding					
	Whichever is smaller	Rated Voltage @25°C, @125°C for 60~120 sec.					
	Dielectric Strength	Dielectric Strength : 250% of the rated voltage for 1~5 seconds					
Board Flex	Appearance : No abnormal exterior appearance	Bending to the limit, 3 mm for 60 seconds 1*					
Board Flex	Capacitance Change Within ±10 %	Initial Measurement 2*					
		Final Measurement 5*					
Terminal	Appearance : No abnormal exterior appearance	10 N, for 60 sec.					
Strength(SMD)	Capacitance Change Within ±10 %	Initial Measurement 2*					
Sa engan(SmD)		Final Measurement 5*					
Beam Load	Destruction value should be exceed 20 N	Beam speed : 0.5±0.05 mm/sec					
Temperature	X7R						
Characteristics	From -55 ℃ to 125 ℃, Capacitance change shou	ld be within ±15%					
0.1010000101000	,						

D. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260 +0/-5 °C, 30sec. ), Meet IPC/JEDEC J-STD-020 D Standard

- \*1 : The figure indicates typical specification. Please refer to individual specifications.
- \*2 : Initial measurement : Perform a heat treatment at 150 +0/-10 °C for one hour after soldering process. and then let sit for 24±2 hours at room temperature. Perform the initial measurement.
- \*3 : Final measurement : Let sit for 24±2 hours at room temperature after test conclusion, then measure.
- \*4 : Final measurement : Perform a heat treatment at 150 +0/-10 °C for one hour after soldering process.
- and then let sit for 24±2 hours at room temperature. Perform the initial measurement.
- \*5 : Final measurement : Let measure within 24 hours at room temperature after test conclusion.

A Product specifications included in the specifications are effective as of March 1, 2013.

- Please be advised that they are standard product specifications for reference only.
- We may change, modify or discontinue the product specifications without notice at any time.
- So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications, please contact our sales personnel or application engineers.

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- Aerospace/Aviation equipment
- ② Medical equipment
- *③ Military equipment*
- ④ Disaster prevention/crime prevention equipment
- *5* Power plant control equipment
- 6 Atomic energy-related equipment
- ⑦ Undersea equipment
- ⑧ Traffic signal equipment
- Data-processing equipment
- 10 Electric heating apparatus, burning equipment
- ${\it I\!\! D}$  Safety equipment
- 2 Any other applications with the same as or similar complexity or reliability to the applications